Exhibition fees

Exhibition fees	1 booth / 9m ² (tax excluded)	
Non-Members	Yen 410,000	
Members' ¹	Yen 350,000	
Other exhibition related expenses		
Corner charge (per corner) ⁻²	Yen 15,000	

How to apply

Please fill out the Application Form in consideration with ofllows:

- Carefully read the "Exhibition Regulations"

- Select the exhibition based on your product

The Secretariat Office will send the invoice. Based on the invoice, please make the payment by the due date.

Deadline -

Thursday, January 31, 2019

Cancellation charges

If an exhibit is cancelled to suit the exhibitor 's circumstances, cancellation charges (full or partial fees) shall apply as belo

Date of receipt of written notice of cancellation	Cancellation charges
By Friday, February 1, 2019	50% of booth fees
From Saturday, February 2, 2019 onward	100% of booth fees

Use of the venue is restricted due to the Olympic and Paralympic Games Tokyo 2020.

Determination of Booth Location

Booth locations will be determined by the organizers based on factors such as the number of exhibition booths, past participation, and membership, and will be announced at the Exhibitors' Briefing.

Exhibition Period

Considering the time required for setting up and removal, the Exhibition is scheduled to be open as follows:

Wednesday, June 5, 10:00 a.m. - 5:00 p.m.

Thursday, June 6, 10:00 a.m. - 5:00 p.m. Friday, June 7, 10:00 a.m. - 4:00 p.m.

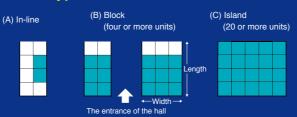
Booth Fixtures and Decorations

To set up and remove your booth efficiently, please cooperate by using a package booth. Details will be informed at a later date.

*1 Members of the WECC member associations (CPCA, EIPC, ELCINA, HKPCA, IPC, IPCA, KPCA and TPCA.)

- *2 Based on availability, corner booth will be reserved. *Please apply early due to limited availability.
- In-line type: 2 side open plan Block type: 3 side open plan
- *If you are allocated a corner booth, the corner booth fee is applied, even if you did not apply for it.

Booth type



Schedule prior to the **Exhibition (Tentative)**

January 31, 2019 Application deadline February 18 Exhibitors' Briefing (Tokyo) February 21 Exhibitors' Briefing (Osaka) Early-April Sending invitations Last-April Deadline for submission of application documents Last-April
June 3 & June 4 Installation period June 5 to June 7 Exhibition open
* Immediate removal on the last day

Reference) Package booth

We are offering the package booths which include the basic furnishings and ornamentation. If you apply for the package booth, you can participate in the Exhibition with little time and effort. Various plans will be made available on the official website

• 1 booth / basic plan

75,000 Yen (excluding tax) This plan includes the minimum necessary booth fixtures and fittings, power supply and carpet.

• 1 booth / upgrade plan

264,000 Yen (excluding tax) This plan includes the booth fixtures and fittings, power supply and carpet and also pays attention to the signage and colors that enhance visibility of a booth.

2 booths / upgrade plan 464,000 Yen (excluding tax) This plan allows the exhibitor to place shelves and inventory spaces according to the exhibitor's



The above prices are fees for furnishing and ornamentation only and does not include the exhibition fee. Specifications and prices are subject to change. Details will be informed at a later date.

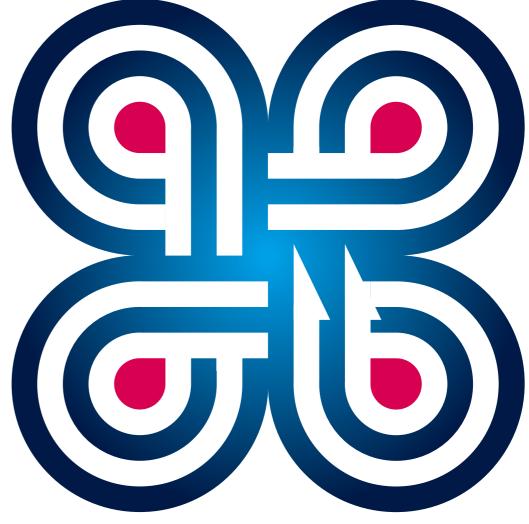




49th International Electronic **Circuits Exhibition**



WIRE Japan Show





6.5 ► 6.7

The Total Solution Exhibition 2

www.jpcashow.com

Managed by

Japan Electronics Packaging and Circuits Association (JPCA)

Kairo Kaikan 2F, 3-12-2, Nishiogikita, Suginami-ku, Tokyo 167-0042 TEL:+81-3-5310-2020 FAX:+81-3-5310-2021 E-mail: show@jpca.org JTB Communication Design, Inc.

Secretariat Office

Celestine Shiba Mitsui Building, 3-23-1, Shiba, Minato-ku, Tokyo, Japan 105-8335 TEL:+81-3-5657-0767 FAX:+81-3-5657-0645 E-mail: jpcashow@jtbcom.co.jp

needs.



Japan Electronics Packaging and Circuits Associatio Organizers Japan Institute of Electronics Packaging, Japan Robot Asso Electronic Device Industry News (Sangyo Times, Inc.), Electric Wire & Cable News (KOGYO TSUSHIN CO., LTD), JTB Communication Design, Inc. Japan Federation Of Electronic Parts Distributors And Dealers Tokyo Electronics Appliances Wholesalers Association Ministry of Economy, Trade and Industry

I ■ Microelectronics Show

33rd ADVANCED ELECTRONICS PACKAGING EXHIBITION

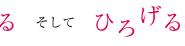


21st Jisson Process Technology Exhibition

Smart Sensing

JEP/TEP Show

Johan Federation Of Electronic Parts Distributors And Dealers
And Dealers
Tokyo Electronics Appliances Wholesalers Association





Tokyo Big Sight West Hall 1-4+Conference Tower



rld Electronic Circuits Council (WECC) Member Ass China Printed Circuit Association (CPCA), European Institute of Printed Circuits (EIPC) ation of India (ELCINA), Hong Kong Pri stries (IPC), Indian Printed Circuit Asso

The Total Solution Exhibition for Electronic Equipment

Comprehensive exhibition of technology embodying IoT, automobile, robots, medical care, wearable, etc.

- Highly specialized and focused
- Exhibition of large attendance from all over the world

2019.6.5 6.7 **Tokyo Big Sight West Hall 1-4+Conference Tower**



Exhibitions held inside the exhibition/relevant exhibits



PWB Tech

Finished Products, Design Technologies, Reliability and Inspection Technologies, Main Materials, Processing, Technologies, Materials, and Equipment, Manufacturing Equipment, Environmental, Systems, Distribution Systems Module JAPAN

Module board, Module Mounting/Design, Module Board/Mounting Materials, Manufacturing and Processing Technologies/Materials and Equipment Distribution and Environmental Systems Flexible Printed Circuits Products Area

EMS Japan

Printed Circuit Mounting Board, Module Mounting Board, Various Integrated Circuits/Mounting/Assembly/Inspection Contract Services



High-density packaging technologies

High-density packaging technologies **Overall High-Density Packaging Technologies** Exhibition Pavilion Academic plaza eX-tech

Electronic Component Packaging Technologies



Electronic Component Packaging Technologies Electronic Component Packaging Machines and Related Equipment/Systems Semiconductor Packaging Machines and Systems

Inspection/Test Equipment Packaging Design Systems

Option **Receive visitor information immediately** after the Show

Information on visitors to your booth will be provided on June 10th (Monday immediately after the exhibition period)!! Utilize the information to send thank-you messages to visitors and providing information at an early phase.

- Made possible by recommending online visitor registration
- Data delivery enables exhibitors to approach visitors immediately

* Details will be informed at the Exhibitors' Briefing

New circuit fabrication technology

Applications of Printed Electronics

LED/OLED/Organic Semiconductor

Materials and Devices/Systems and

Inspection/Evaluation Measurement

Parts, MEMS and Sensors

Design/Analysis Systems

Technologies, etc.

Applications

Total Organic Devices Expo 2019

Main companies visiting the exhibition

- Related to automobile: Aisin Seiki, Asahi Denso, ICHIKOH INDUSTRIES, Calsonic Kansei, Keihin, KOA, KOITO MANUFACTURING, STANLEY ELECTRIC, Sumitomo Wiring Systems, DAIHATSU MOTOR, DENSO, TOKAI RIKA, Tovodenso, TOYOTA MOTOR, NISSAN MOTOR, NHK SPRING, PIONEER, Hitachi Automotive Systems, Hino Motors, SUBARU, Honda Motor, Mazda Motor, MITSUBISHI MOTORS, YAZAKI
- OA/Bohotics: OMBON_KEYENCE, Canon_KONICA MINOLTA, CYBERDYNE, SANYO DENKI, JUKI, SEIKO EPSON, Panasonic, Panasonic Smart Factory Solutions, FANUC FUJI, Fuji Xerox, Mitsubishi Electric, YASKAWA Electric, Yamaha Motor, Ricoh Industry, RICOH JAPAN

Free

- Related to information and communication: Apple, Intel, NHK Media Technology, NTT, NTT DOCOMO, Oki Electric Industry, Korean Broadcasting System (KBS), KYOCERA, KDDI, SoftBank, TOKYO BROADCASTING SYSTEM HOLDINGS (TBS), Toshiba Information Systems (Japan), IBM Japan, NEC, Microsoft Japan, Nihon Unisys, Panasonic, PFU, Hitachi, Huawei, Fujikura, FUJITSU, Murata Manufacturing
- Related to AV and home electrical appliances: LG Electronics, CASIO COMPUTER, Canon, Samsung Electronics, Sharp, Sony, Sony Global Manufacturing & Operations, Sony Semiconductor Solutions, DAIKIN INDUSTRIES, NIKON, PIONEER, Panasonic, FUJITSU GENERAL, YAMAHA, Roland
- Related to medical equipment: Olympus, Siemens, SHIMADZU, SHIRAKAWA OLYMPUS, Terumo, Toshiba Medical Systems, Hitachi High-Technologies, Hitachi Healthcare Manufacturing, Fujifilm, MARK ELECTRONICS, MORITA TOKYO MFG
- Related to semiconductor device: Intel, STMicroelectronics, Canon, Samsung Electronics, SCREEN Holdings, Sony, TDK, Tokyo Electron, Toshiba Memory, NIKON, Hitachi High-Technologies, FUJITSU SEMICONDUCTOR, Micron Japan, Renesas Electronics, ROHM
- Related to aerospace: IHI, NEC Space Technologies, JAXA (Japan Aerospace Exploration Agency), SINFONIA TECHNOLOGY, Nabtesco, Nippon Avionics, NEC, Mitsubishi Heavy Industries. Mitsubishi Electric
- Other: Japan Maritime Self-Defense Force, Japan Ground Self-Defense Force, Tokyo Gas, Tokyo Electric Power, Central Japan Railway, WEST JAPAN RAILWAY, East Japan Railway
- Electronic circuit board: ADVANTEST, Eastern, IBIDEN, ELNA, Kyoei Sangyo, KYOSHA, KYOCERA, Kyoden, Shirai Electronics Industrial, SHINKO, SHINKO ELECTRIC INDUSTRIES, Sumitomo Electric Printed Circuits, DAISHO DENSHI, Nitto Denko, CMK, NIPPON MEKTRON, Panasonic, Hitachi Chemical, Fujikura, FUJITSU INTERCONNECT TECHNOLOGIES. Meiko Electronics. Yamashita Materials. RISHO KOGYO

Electrical/optical transmission technology



Electrical/optical trai

Industrial Equipment and Electric Wires/Cables and Connectors Electric Wire Processors AWM Wire Harness Electric Wires/Cable Measuring Instrument (Electric wire, Cable, Harness) Manufacturing Equipment Inspection machine M2M (Machine to Machine) Optical transmission

www.jpcashow.com

Presentation by exhibitors

The presentation will provide an opportunity to increase your presence at the exhibition.

- Seminar hall (Thirty-minute presentation)
- Equipment for presentation is fully provided.
- Staff are assigned for the seminar reception counter.
- * Lecture time and date can be selected on a first-come-first-served basis.

Sensor technology

Smart Sensing

Sensor technology

- Sensors, Sensor Nodes
- Semiconductors Parts and Devices
- Electronics
- Telecommunications Devices, Network Systems
- Software
- Data Platform
- Power Sources
- Other Related Devices, Technologies and Services

Semiconductors and Electronic parts

JEP/TEP Show

JEP Japan Federation Of Electronic Parts Distributors And Dealer Tokyo Electronics Appliances Wholesalers Association

Semiconductors Electronic Devices Sensors Mechanical Devices FA control equipments Measuring instruments Power Sources IoT and M2M Solution